8-bit Proprietary Microcontroller

CMOS

F²MC-8L MB89660 Series

MB89663/665/P665/W665

■ DESCRIPTION

The MB89660 series has been developed as a general-purpose version of the F²MC*-8L family consisting of proprietary 8-bit single-chip microcontrollers.

In addition to a compact instruction set, the microcontrollers contain a variety of peripheral functions such as timers, a UART, a serial interface, an 8-bit A/D converter, an input capture, an output compare, and an external interrupt. The MB89660 series is applicable to a wide range of applications from welfare products to industrial equipment.

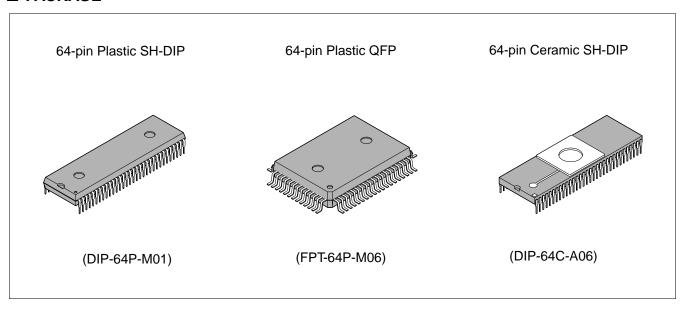
*: F2MC stands for FUJITSU Flexible Microcontroller.

■ FEATURES

 Package expansion QFP package
 SDIP package

(Continued)

■ PACKAGE



(Continued)

F²MC-8L family CPU core

Instruction set optimized for controllers

Multiplication and division instructions
16-bit arithmetic operations
Test and branch instructions
Bit manipulation instructions, etc.

- Three types of timers
 8-bit PWM timer
 8/16-bit timer/counter
 20-bit time-base timer
- Functions that permit communications with a variety of devices
 UART which permits selection of synchronous/asynchronous communications
 A serial interface that permits selection of the transfer direction
- 8-bit A/D converter: 8 channels Sense mode function capable of performing compare operation in 5 μ s Activation by external input possible
- · Real-time control

Input capture: 2 channels
Output compare: 2 channels

• External interrupt: 4 channels

Two channels are independent and capable of wake-up from low-power consumption modes (with an edge detection function).

• Low power consumption modes

Stop mode (Oscillation stops to minimize the current consumption.)

Sleep mode (The CPU stops to reduce the current consumption to approx. 1/3 of normal.)

Hardware standby mode (Wake-up from this mode and activation by pin input only.)

■ PRODUCT LINEUP

Part number Parameter	MB89663	MB89665	MB89W665	MB89P665	
Classification		tion products If products)	EPROM product	One-time PROM product, also used for evaluation	
ROM size	8 K × 8 bits (internal mask ROM)	16 K × 8 bits (internal mask ROM)	16 K × 8 bits (internal PROM, programming with general-purpose EPROM programmer)	16 K × 8 bits (internal PROM, programming with general-purpose EPROM programmer)	
RAM size	256 × 8 bits		512 × 8 bits		
CPU functions	Instruction Instruction Data bit ler Minimum e	length:	136 8 bits 1 to 3 bytes 1,8, 16 bits 0.4 μs/10 MHz 3.6 μs/10 MHz		
Ports	Output port Output port I/O ports (C Total:	ts (N-ch open-drain):	8 8 (All also serve as p 36 (19 ports also serves 52		
8-bit PWM timer			ble, operating clock cycle: version cycle: 102 μs, 1		
8/16-bit timer/ counter	Single	16-bit event counter (ca One clock selectable fr	r/counter operation: 2 chascade connection): 1 crom four transfer clocks rnal clocks: 0.8 µs, 3.2	hannel	
UART	8 bits Full-duplex double buffer Synchronous and asynchronous data transfer				
8-bit serial I/O	8 bits LSB first/MSB first selectability One clock selectable from four transfer clocks (one external shift clock, three internal shift clocks: 0.8 μs, 3.2 μs, 12.8 μs)				
8-bit A/D converter	8-bit resolution × 8 channels A/D conversion mode (conversion time: 18 μs at 10 MHz) Sense mode (conversion time: 5 μs at 10 MHz) Continuous activation by an external activation or an internal timer capable Reference voltage input				
Real-time I/O		overflow re: 16 bits × 2 channels	le (0.4 μs, 0.8 μs, 1.6 μs interrupt (External trigger edge s 6 bits × 2 channels	• •	

(Continued)

Part number Parameter	MB89663	MB89665	MB89W665	MB89P665	
External interrupt	F	4 channels (edge selection, interrupt vector, source flag) Rising edge/falling edge/both edges selectability Used also for wake-up from stop/sleep mode. (Edge detection is also permitted in stop mode.) (Wake-up from hardware standby mode is not possible)			
Standby mode	Sleep mode, stop mode, and hardware standby mode				
Process	CMOS				
Operating voltage*	2.2 V t	o 6.0 V	2.7 V t	o 6.0 V	

^{*:} Varies with conditions such as the operating frequency. (See section "■ Electrical Characteristics.")

■ PACKAGE AND CORRESPONDING PRODUCTS

Package	MB89663 MB89665 MB89P665	MB89W665
DIP-64P-M01	0	×
DIP-64C-A06	×	0
FPT-64P-M06	0	×

○ : Available ×: Not available

Note: For more information about each package, see section "■ Package Dimensions."

■ DIFFERENCES AMONG PRODUCTS

1. Memory Size

Before evaluating using the OTPROM (one-time PROM) product (also used for evaluation), verify its differences from the product that will actually be used: Take particular care on the following points:

- On the MB89663, register bank from 16 to 32 cannot be used.
- On the MB89P665, address BFF0_H to BFF6_H comprise the option setting area, option settings can be read by reading these addresses.
- The stack area, etc., is used.

2. Current Consumption

- When operated at low speed, the product with an OTPROM or an EPROM will consume more current than the product with a mask ROM.
- However, the current comsumption in sleep/stop modes is the same. (For more information, see sections
 "■ Electrical Characteristics" and "■ Example Characteristics."

3. Mask Options

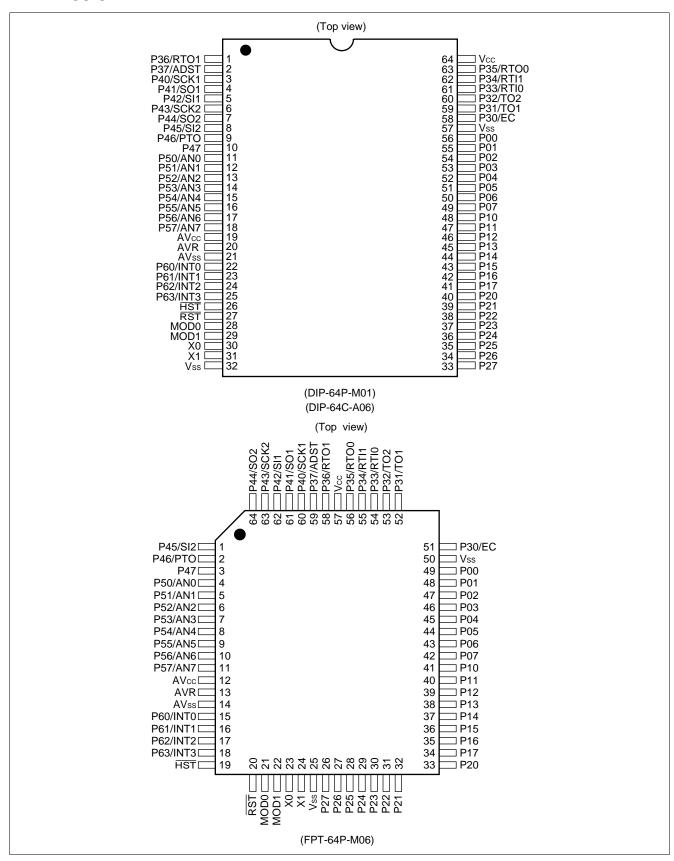
Functions that can be selected as options and how to designate these options vary by the product.

Before using options check section "■ Mask Options."

Take particular care on the following points:

- On the MB89P665, a pull-up resistor must be selected in a group of four pins for P54 to P57.
- For all products, P50 to P57 must be set to without a pull-up resistor when an A/D converter is used.

■ PIN ASSIGNMENT



■ PIN DESCRIPTION

Pin no.		Pin name Circuit		Function	
DIP*1	QFP*2	Pin name	type	Function	
30	23	X0	Α	Crystal oscillator pins	
31	24	X1			
28	21	MOD0	В	Operating mode selection pins	
29	22	MOD1		Connect directly to Vcc or Vss. A pull-down resistor is selectable as an option for mask ROM products.	
27	20	RST	С	Reset I/O pin This port is an N-ch open-drain output type with pull-up resistor and a hysteresis input type. "L" is output from this pin by an internal reset source. The internal circuit is initialized by the input of "L".	
26	19	HST	G	Hardware standby input pin Connect directly to Vcc when hardware standby is not used.	
56 to 49	49 to 42	P00 to P07	D	General-purpose I/O ports	
48 to 41	41 to 34	P10 to P17			
40 to 33	33 to 26	P20 to P27	F	General-purpose output ports	
58	51	P30/EC	E	General-purpose I/O port Also serves as an external clock input for an 8/16-bit timer/counter. This pin is a hysteresis input type and with a noise canceller.	
59	52	P31/TO1	Е	General-purpose high-current I/O port Also serves as an 8/16-bit timer/counter output. This pin is a hysteresis input type and with a noise canceller.	
60	53	P32/TO2	E	General-purpose I/O port Also serves as an 8/16-bit timer/counter output. This pin is a hysteresis input type and with a noise canceller.	
61	54	P33/RTI0	E	General-purpose I/O ports	
62	55	P34/RTI1		Also serve as the data input for the input capture. This pin is a hysteresis input type and with a noise canceller.	
63	56	P35/RTO0	E	General-purpose I/O ports	
1	58	P36/RTO1		Also serve as the data output for the output compare. This pin is a hysteresis input type and with a noise canceller.	
2	59	P37/ADST	E	General-purpose heavy-current I/O port Also serves as the external activation input for the A/D converter. This pin is a hysteresis input type and with a noise canceller.	

*1: DIP-64P-M01, DIP-64C-A06

(Continued)

*2: FPT-64P-M06

Pin	no.	Din name Circuit		Function	
DIP*1	QFP*2	Pin name	type	Function	
3	60	P40/SCK1	E	General-purpose I/O port Also serves as the clock I/O for the UART. This pin is a hysteresis input type and with a noise canceller.	
4	61	P41/SO1	E	General-purpose I/O port Also serves as the data output for the UART. This pin is a hysteresis input type and with a noise canceller.	
5	62	P42/SI1	E	General-purpose I/O port Also serves as the data input for the UART. This pin is a hysteresis input type and with a noise canceller.	
6	63	P43/SCK2	Е	General-purpose I/O port Also serves as the clock I/O for the 8-bit serial I/O interface. This pin is a hysteresis input type and with a noise canceller.	
7	64	P44/SO2	Е	General-purpose I/O port Also serves as the data output for the 8-bit serial I/O interface. This pin is a hysteresis input type and with a noise canceller.	
8	1	P45/SI2	E	General-purpose I/O port Also serves as the data input for the 8-bit serial I/O interface. This pin is a hysteresis input type and with a noise canceller.	
9	2	P46/PTO	Е	General-purpose I/O port Also serves as a toggle output for an 8-bit PWM timer. This pin is a hysteresis input type and with a noise canceller.	
10	3	P47	E	General-purpose I/O port This pin is a hysteresis input type and with a noise canceller.	
11 to 18	4 to 11	P50/AN0 to P57/AN7	Н	N-ch open-drain output-only ports Also serve as the analog input for the A/D converter.	
22 to 25	15 to 18	P60/INT0 to P63/INT3	Е	General-purpose I/O ports These pins also serve as an external interrupt input. These pins are a hysteresis input type and with a noise canceller.	
64	57	Vcc	_	Power supply pin	
32 57	25 50	Vss	_	Power supply (GND) pins	
19	12	AVcc	_	A/D converter power supply pin	
20	13	AVR	_	A/D converter reference voltage input pin	
21	14	AVss	_	A/D converter power supply pin Use this pin at the same voltage as Vss.	

^{*1:} DIP-64P-M01, DIP-64C-A06

^{*2:} FPT-64P-M06

■ I/O CIRCUIT TYPE

Туре	Circuit	Remarks
A	X1 X0 X0 X1 X1 X0 X1 X1 X1 X1 X1 X1 X1 X1 X1 X1 X1 X1 X1	 External clock input selection versions of crystal or ceramic oscillation type At an oscillation feedback resistor of approximately 1 MΩ/5.0 V
В		CMOS input Built-in pull-down resistor (mask ROM products only)
С	R P-ch N-ch	 At an output pull-up resistor (P-ch) of approximately 50 kΩ/5.0 V Hysteresis input
D	P-ch N-ch	 CMOS output CMOS input Pull-up resistor optional
E	P-ch P-ch	CMOS output Hysteresis input Pull-up resistor optional
F	P-ch N-ch	CMOS output

Туре	Circuit	Remarks
G		Hysteresis input
Н	P-ch N-ch Analog input	 N-ch open-drain output Analog input Pull-up resistor optional

■ HANDLING DEVICES

1. Preventing Latchup

Latchup may occur on CMOS ICs if voltage higher than V_{cc} or lower than V_{ss} is applied to input and output pins other than medium- or high-voltage pins or if higher than the voltage which shows on "1. Absolute Maximum Ratings" in section "■ Electrical Characteristics" is applied between V_{cc} and V_{ss}.

When latchup occurs, power supply current increases rapidly and might thermally damage elements. When using, take great care not to exceed the absolute maximum ratings.

Also take care to prevent the analog power supply (AVcc and AVR) and analog input from exceeding the digital power supply (Vcc) when the analog system power supply is turned on and off.

2. Treatment of Unused Input Pins

Leaving unused input pins open could cause malfunctions. They should be connected to a pull-up or pull-down resistor.

3. Treatment of Power Supply Pins on Microcontrollers with A/D Converters

Connect to be AVcc = Vcc and AVss = AVR = Vss if the A/D converters are not in use.

4. Power Supply Voltage Fluctuations

Although Vcc power supply voltage is assured to operate within the rated range, a rapid fluctuation of the voltage could cause malfunctions, even if it occurs within the rated range. Stabilizing voltage supplied to the IC is therefore important. As stabilization guidelines, it is recommended to control power so that Vcc ripple fluctuations (P-P value) will be less than 10% of the standard Vcc value at the commercial frequency(50 to 60 Hz) and the transient fluctuation rate will be less than 0.1 V/ms at the time of a momentary fluctuation such as when power is switched.

5. Precautions when Using an External Clock

Even when an external clock is used, oscillation stabilization time is required for power-on reset (optional) and wake-up from stop mode.

■ PROGRAMMING TO THE EPROM ON THE MB89P665

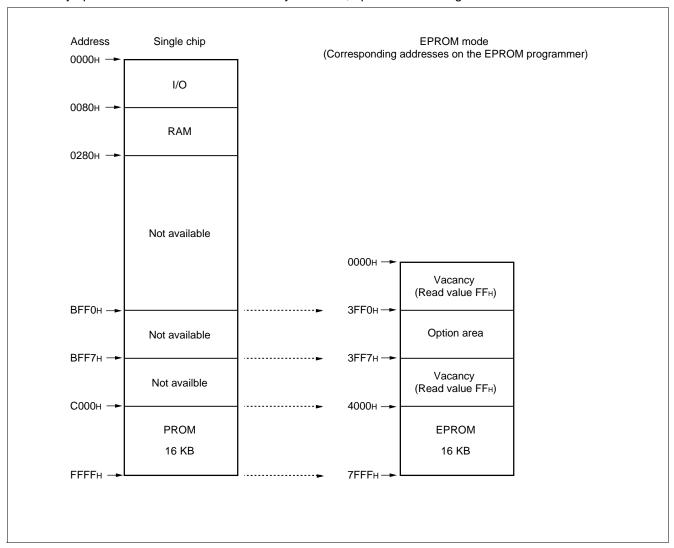
The MB89P665 is an OTPROM version of the MB89660 series.

1. Features

- 16-Kbyte PROM on chip
- Options can be set using the EPROM programmer.
- Equivalency to the MBM27C256A in EPROM mode (when programmed with the EPROM programmer)

2. Memory Space

Memory space in each mode such as 16-Kbyte PROM, option area is diagrammed below.



3. Programming to the PROM

In EPROM mode, the MB89P665A functions equivalent to the MBM27C256A. This allows the PROM to be programmed with a general-purpose EPROM programmer (the electronic signature mode cannot be used) by using the dedicated socket adapter.

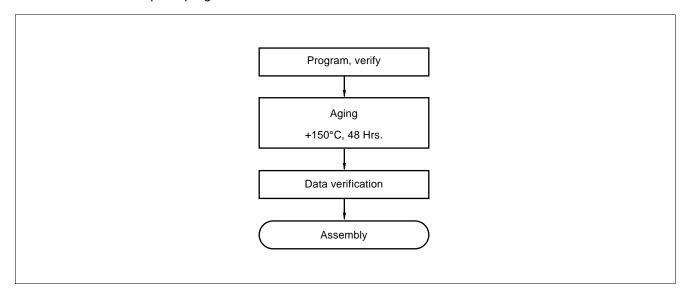
• Programming procedure

- (1) Set the EPROM programmer to the MBM27C256A.
- (2) Load program data into the EPROM programmer at 4000H to 7FFFH (note that addresses C000H to FFFFH while operating as a single chip assign to 4000H to 7FFFH in EPROM mode).

 Load option data into addresses 3FF0H to 3FF6H of the EPROM programmer. (For information about each corresponding option, see "8. Setting OTPROM Options.")
- (3) Program with the EPROM programmer.

4. Recommended Screening Conditions

High-temperature aging is recommended as the pre-assembly screening procedure for a product with a blanked OTPROM microcomputer program.



5. Programming Yield

All bits cannot be programmed at Fujitsu shipping test to a blanked OTPROM microcomputer, due to its nature. For this reason, a programming yield of 100% cannot be assured at all times.

6. Erasure Procedure

In order to clear all locations of their programmed contents, it is necessary to expose the internal EPROM to an ultraviolet light source. A dosage of 10 W-seconds/cm² is required to completely erase an internal EPROM. This dosage can be obtained by exposure to an ultraviolet lamp (wavelength of 2537 Angstroms (Å)) with intensity of 12000 μ W/cm² for 15 to 21 minuites. The internal EPROM should be about one inch from the source and all filters should be removed from the UV light source prior to erasure.

It is important to note that the internal EPROM and similar devices, will erase with light sources having wavelengths shorter than 4000 Å. Although erasure time will be much longer than with UV source at 2537 Å, nevertheless the exposure to fluorescent light and sunlight will eventually erase the internal EPROM, and exposure to them should be prevented to realize maximum system reliability. If used in such an environment, the package windows should be covered by an opaque label or substance.

7. EPROM Programmer Socket Adapter

Package	Compatible socket adapter
FPT-64P-M06	ROM-64QF-28DP-8L
DIP-64P-M01	ROM-64SD-28DP-8L

Inquiry: Sun Hayato Co., Ltd.: TEL 81-3-3802-5760 Note: Connect the adapter jumper pin to Vss when using.

8. Setting OTPROM Options

The programming procedure is the same as that for the PROM. Options can be set by programming values at the addresses shown on the memory map. The relationship between bits and options is shown on the following bit map:

• OTPROM option bit map

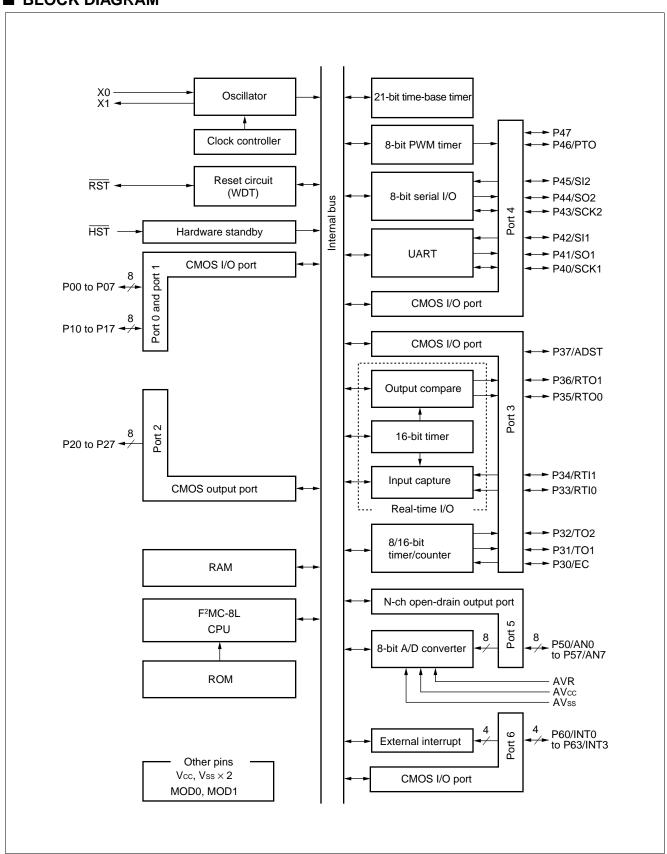
	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
3FF0н	Vacancy Readable and writable	Vacancy Readable and writable	Vacancy Readable and writable	Oscillation stabilization time 1: Crystal 0: Ceramic	Reset pin output 1: Yes 0: No	Power-on reset 1: Yes 0: No	Vacancy Readable and writable	Vacancy Readable and writable
3FF1н	P07	P06	P05	P04	P03	P02	P01	P00
	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up
	1: No	1: No	1: No	1: No	1: No	1: No	1: No	1: No
	1: Yes	1: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes
3FF2н	P17	P16	P15	P14	P13	P12	P11	P10
	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up
	1: No	1: No	1: No	1: No	1: No	1: No	1: No	1: No
	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes
3FF3н	P37	P36	P35	P34	P33	P32	P31	P30
	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up
	1: No	1: No	1: No	1: No	1: No	1: No	1: No	1: No
	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes
3FF4н	P47	P46	P45	P44	P43	P42	P41	P40
	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up
	1: No	1: No	1: No	1: No	1: No	1: No	1: No	1: No
	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes
3FF5н	Vacancy Readable and writable	Vacancy Readable and writable	Vacancy Readable and writable	P57 to P54 Pull-up 1: No 0: Yes	P53 Pull-up 1: No 0: Yes	P52 Pull-up 1: No 0: Yes	P51 Pull-up 1: No 0: Yes	P50 Pull-up 1: No 0: Yes
3FF6н	Vacancy Readable and writable	Vacancy Readable and writable	Vacancy Readable and writable	Vacancy Readable and writable	P63 Pull-up 1: No 0: Yes	P62 Pull-up 1: No 0: Yes	P61 Pull-up 1: No 0: Yes	P60 Pull-up 1: No 0: Yes

Note: • Set each bit to erase.

• Do not write 0 to the vacant bit.

The read value of the vacant bit is 1, unless 0 is written to it.

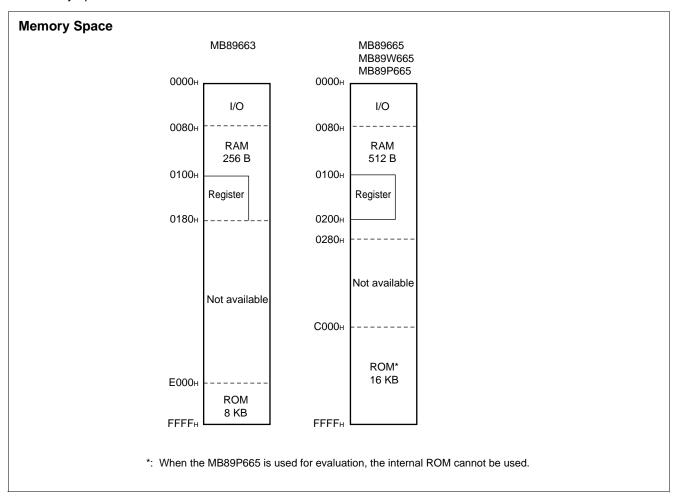
■ BLOCK DIAGRAM



■ CPU CORE

1. Memory Space

The microcontrollers of the MB89660 series offer a memory space of 64 Kbytes for storing all of I/O, data, and program areas. The I/O area is located at the lowest address. The data area is provided immediately above the I/O area. The data area can be divided into register, stack, and direct areas according to the application. The program area is located at exactly the opposite end, that is, near the highest address. Provide the tables of interrupt reset vectors and vector call instructions toward the highest address within the program area. The memory space of the MB89660 series is structured as illustrated below.



2. Registers

The F²MC-8L family has two types of registers; dedicated registers in the CPU and general-purpose registers in the memory. The following dedicated registers are provided:

Program counter (PC): A 16-bit register for indicating instruction storage positions

Accumulator (A): A 16-bit temporary register for storing arithmetic operations, etc. When the

instruction is an 8-bit data processing instruction, the lower byte is used.

Temporary accumulator (T): A 16-bit register which performs arithmetic operations with the accumulator

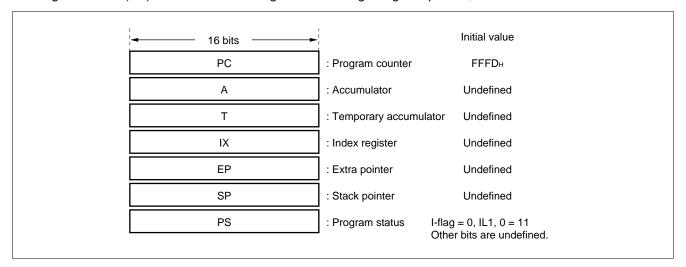
When the instruction is an 8-bit data processing instruction, the lower byte is used.

Index register (IX): A 16-bit register for index modification

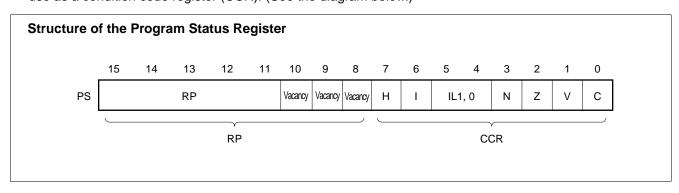
Extra pointer (EP): A 16-bit pointer for indicating a memory address

Stack pointer (SP): A 16-bit register for indicating a stack area

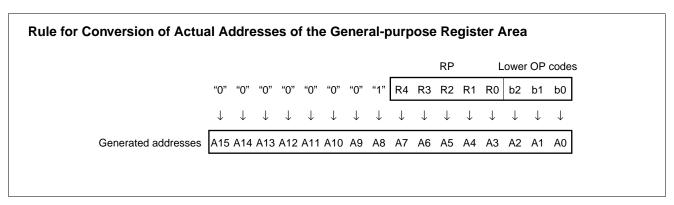
Program status (PS): A 16-bit register for storing a register pointer, a condition code



The PS can further be divided into higher 8 bits for use as a register bank pointer (RP) and the lower 8 bits for use as a condition code register (CCR). (See the diagram below.)



The RP indicates the address of the register bank currently in use. The relationship between the pointer contents and the actual address is based on the conversion rule illustrated below.



The CCR consists of bits indicating the results of arithmetic operations and the contents of transfer data and bits for control of CPU operations at the time of an interrupt.

H-flag: Set when a carry or a borrow from bit 3 to bit 4 occurs as a result of an arithmetic operation. Cleared otherwise. This flag is for decimal adjustment instructions.

I-flag: Interrupt is allowed when this flag is set to 1. Interrupt is prohibited when the flag is set to 0. Set to 0 when reset.

IL1, 0: Indicates the level of the interrupt currently allowed. Processes an interrupt only if its request level is higher than the value indicated by this bit.

IL1	IL0	Interrupt level	High-low
0	0	1	High
0	1		†
1	0	2	
1	1	3	Low = no interrupt

N-flag: Set if the MSB is set to 1 as the result of an arithmetic operation. Cleared when the bit is set to 0.

Z-flag: Set when an arithmetic operation results in 0. Cleared otherwise.

V-flag: Set if the complement on 2 overflows as a result of an arithmetic operation. Reset if the overflow does not occur.

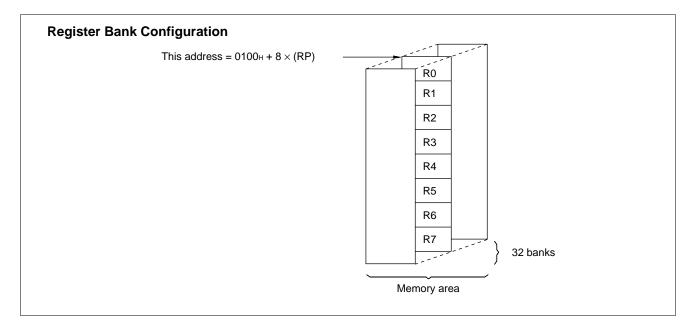
C-flag: Set when a carry or a borrow from bit 7 occurs as a result of an arithmetic operation. Cleared otherwise. Set to the shift-out value in the case of a shift instruction.

The following general-purpose registers are provided:

General-purpose registers: an 8-bit register for storing data

The general-purpose registers are 8 bits and located in the register banks of the memory. One bank contains eight registers. Up to a total of 16 banks can be used on the MB89663 and a total of 32 banks can be used on the MB89665/P665/W665. The bank currently in use is indicated by the register bank pointer (RP).

Note: The number of register banks that can be used varies with the RAM size.



■ I/O MAP

Address	Read/write	Register name	Register description
00н	(R/W)	PDR0	Port 0 data register
01н	(W)	DDR0	Port 0 data direction register
02н	(R/W)	PDR1	Port 1 data register
03н	(W)	DDR1	Port 1 data direction register
04н	(R/W)	PDR2	Port 2 data register
05н			Vacancy
06н			Vacancy
07н			Vacancy
08н	(R/W)	STBC	Standby control register
09н	(R/W)	WDTC	Watchdog timer control register
ОАн	(R/W)	TBTC	Watch interrupt control register
0Вн			Vacancy
0Сн	(R/W)	PDR3	Port 3 data register
0Dн	(W)	DDR3	Port 3 data direction register
0Ен	(R/W)	PDR4	Port 4 data register
0Fн	(W)	DDR4	Port 4 data direction register
10н	(R/W)	PDR5	Port 5 data register
11н			Vacancy
12н	(R/W)	PDR6	Port 6 data register
13н	(W)	DDR6	Port 6 data direction register
14н			Vacancy
15н	(R/W)	ADC1	A/D converter control register 1
16н	(R/W)	ADC2	A/D converter control register 2
17н	(R/W)	ADCD	A/D converter data register
18н	(R/W)	T2CR	8/16-bit timer 2 control register
19н	(R/W)	T1CR	8/16-bit timer 1 control register
1Ан	(R/W)	T2DR	8/16-bit timer 2 data register
1Вн	(R/W)	T1DR	8/16-bit timer 1 data register
1Сн	(R/W)	CNTR	PWM control register
1Dн	(W)	COMR	PWM compare register
1Ен			Vacancy
1Fн			Vacancy

(Continued)

Address	Read/write	Register name	Register description	
20н	(R/W)	SMC	UART serial mode control register	
21н	(R/W)	SRC	UART serial rate control register	
22н	(R/W)	SSD	UART serial status/data register	
23н	(R/W)	SIDR/SODR	UART serial data register	
24н	(R/W)	SMR	Serial mode register	
25н	(R/W)	SDR	Serial data register	
26н	(R/W)	EIC1	External interrupt control register 1	
27н	(R/W)	EIC2	External interrupt control register 2	
28н	(R/W)	TMCR	Timer control register	
29н	(R)	TCHR	Timer count register (H)	
2Ан	(R)	TCLR	Timer count register (L)	
2Вн	(R/W)	OPCR	Output control register	
2Сн	(R/W)	CPR0H	Output compare register 0 (H)	
2Dн	(R/W)	CPR0L	Output compare register 0 (L)	
2Ен	(R/W)	CPR1H	Output compare register 1 (H)	
2Fн	(R/W)	CPR1L	Output compare register 1 (L)	
30н	(R/W)	ICCR	Input capture control register	
31н	(R/W)	ICIC	Input capture interrupt control register	
32н	(R)	ICR0H	Input capture register 0 (H)	
33н	(R)	ICR0L	Input capture register 0 (L)	
34н	(R)	ICR1H	Input capture register 1 (H)	
35н	(R)	ICR1L	Input capture register 1 (L)	
36н			Vacancy	
37н		Vacancy		
38н			Vacancy	
7Сн	(W)	ILR1	Interrupt level setting register 1	
7Dн	(W)	ILR2	Interrupt level setting register 2	
7Ен	(W)	ILR3	Interrupt level setting register 3	
7 Fн			Vacancy	

Note: Do not use vacancies.

■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

(AVss = Vss = 0.0 V)

Parameter	Symbol	Va	lue	Unit	Remarks
i didilietei	Symbol	Min.	Max.	Oilit	itelliai ks
Power supply voltage	Vcc AVcc	Vss - 0.3	Vss + 7.0	V	*
	AVR	Vss - 0.3	Vss + 7.0	V	AVR must not exceed AVcc + 0.3 V
Input voltage	Vı	Vss - 0.3	Vcc + 0.3	V	
Output voltage	Vo	Vss - 0.3	Vcc + 0.3	V	
"L" level maximum output current	Іоь	_	20	mA	
"L" level average output current	lolav	_	4	mA	Average value (operating current × operating rate)
"L" level total maximum output current	ΣΙοι	_	100	mA	
"L" level total average output current	ΣΙοιαν	_	40	mA	Average value (operating current × operating rate)
"H" level maximum output current	Іон	_	-20	mA	
"H" level average output current	Іонач	_	-4	mA	Average value (operating current × operating rate)
"H" level total maximum output current	ΣІон	_	-50	mA	
"H" level total average output current	ΣΙομαν	_	-20	mA	Average value (operating current × operating rate)
Power consumption	PD	_	300	mW	
Operating temperature	TA	-40	+85	°C	
Storage temperature	Tstg	-55	+150	°C	

^{*:} Use AVcc and Vcc set at the same voltage.

Take care so that AVcc does not exceed Vcc, such as when power is turned on.

Precautions: Permanent device damage may occur if the above "Absolute Maximum Ratings" are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

2. Recommended Operating Conditions

(AVss = Vss = 0.0 V)

Parameter	Symbol	Va	lue	Unit	Remarks
raiametei	Syllibol	Min.	Max.	Offic	Nemai ka
		2.2*	6.0*	V	Normal operation assurance range* MB89663/665
Power supply voltage	Vcc AVcc	2.7*	6.0*	V	Normal operation assurance range* MB89P665
		1.5	6.0	٧	Retains the RAM state in stop mode
	AVR	0.0	AVcc	V	
Operating temperature	TA	-40	+85	°C	

^{*:} These values vary with the operating frequency and analog assurance range. See Figure. 1 and "5. A/D Converter Electrical Characteristics."

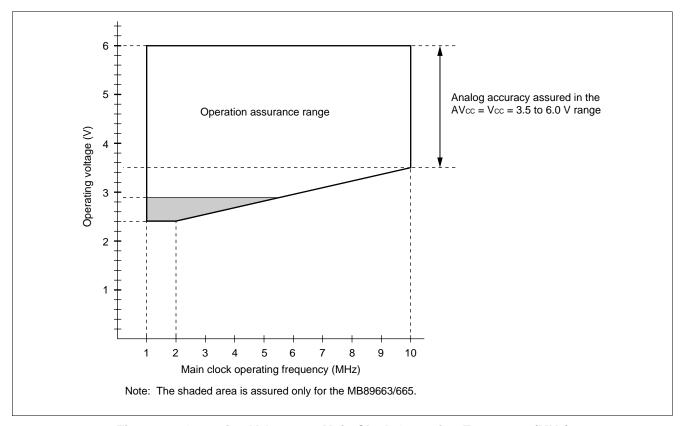


Figure 1 Operating Voltage vs. Main Clock Operating Frequency (MHz)

3. DC characteristics

 $(AVcc = Vcc = +5.0 \text{ V}, AVss = Vss = 0.0 \text{ V}, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

			,	<u> </u>	Value	<u> </u>		40°C to +85°C)
Parameter	Symbol	Pin	Condition	Min.	Тур.	Max.	Unit	Remarks
	ViH	P00 to P07, P10 to P17	_	0.7 Vcc	_	Vcc + 0.3	V	
"H" level input voltage	Vihs	RST, HST P30 to P37, P40 to P47, P60 to P63	_	0.8 Vcc	_	Vcc + 0.3	V	
	VIL	P00 to P07, P10 to P17	_	Vss - 0.3	_	0.3 Vcc	V	
"L" level input voltage*1	VILS	RST, HST P30 to P37, P40 to P47, P60 to P63	_	Vss - 0.3	_	0.2 Vcc	V	
Open-drain output pin application voltage	VD	P50 to P57	_	Vss - 0.3	_	Vcc + 0.3	V	
"H" level output Vон1 voltage	V _{OH1}	P00 to P07, P10 to P17, P20 to P27, P30, P32 to P36, P40 to P47, P60 to P63	Iон = -2.0 mA	2.4	_	_	V	
	V _{OH2}	P31, P37	Iон = −15 mA	2.4	_	_	V	
"L" level output voltage	Vol1	P00 to P07, P10 to P17, P20 to P27, P30, P32 to P36, P40 to P47, P50 to P57, P60 to P63	IoL = +1.8 mA	_	_	0.4	V	
	V _{OL2}	P31, P37	loL = +12 mA	_	_	0.4	V	
	Vol3	RST	IoL = +4.0 mA	_	_	0.4	V	
Input leakage current (Hi-z output leakage current)	Іш	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P60 to P63	0.45 V < Vı < Vcc	_	_	±5	μА	Without pull-up resistor
Pull-up resistance	Rpulu	RST, option selection pin	Vı = 0.0 V	25	50	100	kΩ	

(Continued)

 $(AVcc = Vcc = +5.0 \text{ V}, AVss = Vss = 0.0 \text{ V}, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

Davamatar	0	mbal Din	,		Value			40 C t0 +85 C)
Parameter	Symbol	Pin	Condition	Min.	Тур.	Max.	Unit	Remarks
Pull-down resistance	Rpuld	MOD0, MOD1	Vı = +5.0 mA	5	20	60	kΩ	Mask ROM products only
			Fc = 10 MHz	_	15	18	mA	MB89663/665
	Icc	t _{inst} *3 = 0.4 μs Normal mode	_	17	20	mA	MB89P665/ W665	
Icc	Iccs	Vcc	$F_C = 10 \text{ MHz}$ $t_{inst}^{*3} = 0.4 \mu s$ Sleep mode	_	6	8	mA	
Power supply current			$T_A = +25^{\circ}C$ $t_{inst}^{*3} = 0.4 \mu s$ Stop mode	_	_	10	μА	Also applicable to the hardware standby mode.
			Fc = 10 MHz, when A/D conversion is activated	_	2.5	4.5	mA	
la	Iан	AVcc	Fc = 10 MHz, T _A = +25°C, when A/D conversion is stopped	_	_	5	μА	
Input capacitance	Cin	Other than AVcc, AVss, Vcc, and Vss	f = 1 MHz	_	10	-	pF	

^{*1:} Fix MOD0 and MOD1 to Vss.

^{*2:} The power supply current is measured at the external clock.

^{*3:} For information on t_{inst}, see "(4) Instruction Cycle" in "4. AC Characteristics."

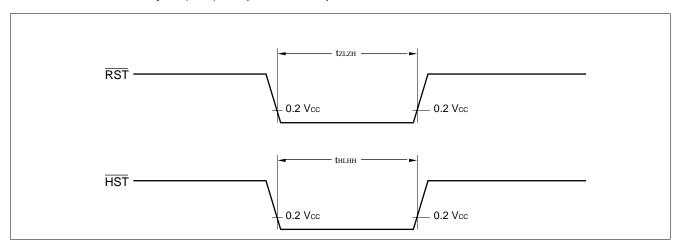
4. AC Characteristics

(1) Reset Timing, Hardware Standby Timing

 $(Vcc = +5.0 V\pm 10\%, AVss = Vss = 0.0 V, TA = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Condition	Va	lue	Unit	Remarks
	Syllibol	Condition	Min.	Max.	Offic	Remarks
RST "L" pulse width	t zlzh		16 txcyl	_	ns	
HST "L" pulse width	tньнн	<u> </u>	16 txcyl	_	ns	

^{*:} txcyL is the oscillation cycle (1/Fc) to input to the X0 pin.



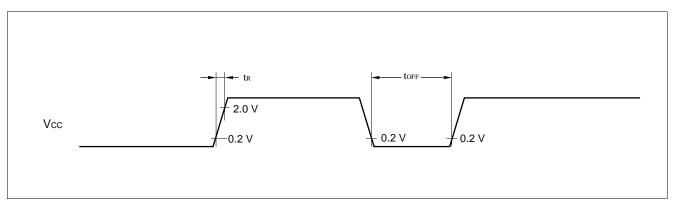
(2) Power-on Reset

 $(AVss = Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Condition	Val	ues	Unit	Remarks	
raiailletei	Syllibol	Condition	Min.	Max.	Ollit	Neillai KS	
Power supply rising time	t R		_	50	ms		
Power supply cut-off time	t off	-	1	_	ms	Due to repeated operations	

Note: Make sure that power supply rises within the selected oscillation stabilization time.

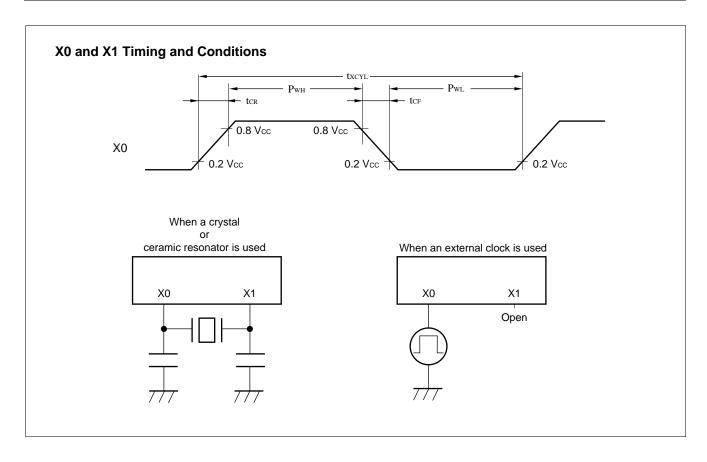
If power supply voltage needs to be varied in the course of operation, a smooth voltage rise is recommended.



(3) Clock Timing

 $(AVss = Vss = 0.0 \text{ V}, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

Parameter	Symbol	Pin	Condition		Value		Unit	Remarks
Farameter	Syllibol	FIII	Condition	Min.	Тур.	Max.	Oilit	
Clock frequency	Fc	X0, X1	_	1	_	10	MHz	
Clock cycle time	txcyL	X0, X1	_	100	_	1000	ns	
Input clock pulse width	P _{WH} P _{WL}	X0	_	20	_	_	ns	External clock
Input clock rising/ falling time	tcr tcr	X0	_	_	_	10	ns	External clock

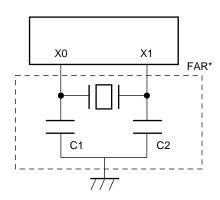


(4) Instruction Cycle

Parameter	Symbol	Value (typical)	Unit	Remarks
Instruction cycle (minimum execution time)	t inst	4/Fc	μs	When operating at Fc = 10 MHz

(5) Recommended Resonator Manufacturers

Sample Application of Piezoelectric Resonator (FAR series)

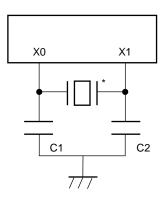


*: Fujitsu Acoustic Resonator C1 = C2 = 20 pF±8 pF (built-in FAR)

FAR part number (built-in capacitor type)	Frequency	Initial deviation of FAR frequency (T _A = +25°C)	Temperature characteristic of FAR frequency (T _A = -20°C to +60°C)
FAR-C4CB-08000-M02	8.00 MHz	±0.5%	±0.5%
FAR-C4CB-10000-M02	10.00 MHz	±0.5%	±0.5%

Inquiry: FUJITSU LIMITED

Sample Application of Ceramic Resonator



Resonator manufacturer*	Resonator	Frequency	C1 (pF)	C2 (pF)	R (k Ω)
Kyocera Corporation	KBR-7.68MWS	7.68 MHz	33	33	_
Ryocera Corporation	KBR-8.0MWS	8.0 MHz	33	33	_
Murata Mfg. Co., Ltd.	CSA8.00MTZ	8.0 MHz	30	30	_

Inquiry: Kyocera Corporation

• AVX Corporation

North American Sales Headquarters: TEL 1-803-448-9411

AVX Limited

European Sales Headquarters: TEL 44-1252-770000

• AVX/Kyocera H.K. Ltd.

Asian Sales Headquarters: TEL 852-363-3303

Murata Mfg. Co., Ltd.

Murata Electronics North America, Inc.: TEL 1-404-436-1300
Murata Europe Management GmbH: TEL 49-911-66870

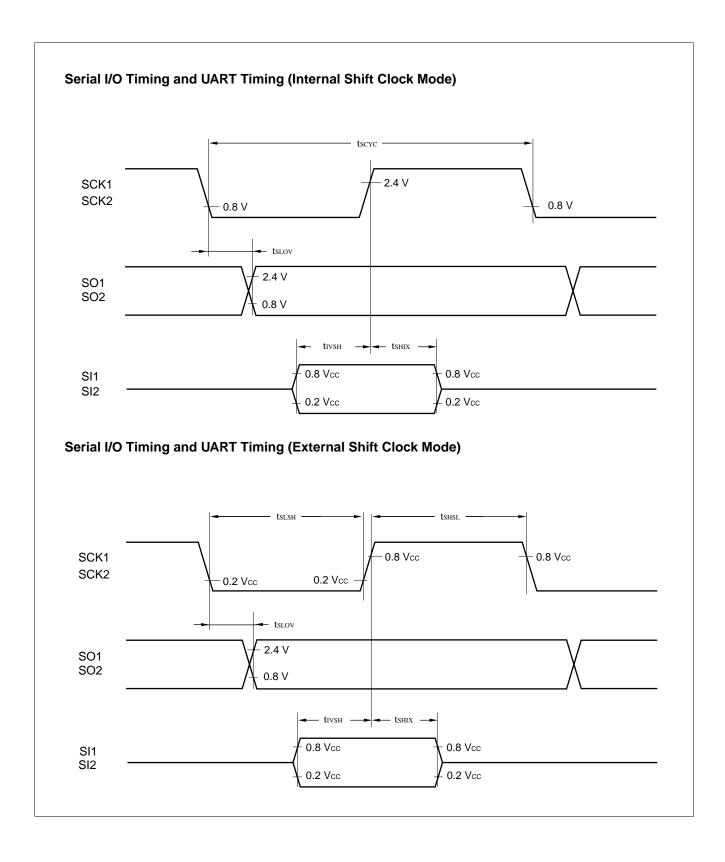
• Murata Electronics Singapore (Pte.) Ltd.: TEL 65-758-4233

(6) Serial I/O Timing and UART Timing

 $(Vcc = +5.0 V\pm 10\%, AVss = Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

		(•	VCC = +5.0 V±1076, AVSS = VSS =			, ix	10 0 10 100 0
Parameter	Symbol	Pin	Condition	Val	ue	Unit	Remarks
i didilictor	Cymbol	1 111	Condition	Min.	Max.	Oiiit	Kemarks
Serial clock cycle time	tscyc	SCK1, SCK2		2 tinst*	_	μs	
$\begin{array}{c} SCK1 \downarrow \to SO1 \text{ time} \\ SCK2 \downarrow \to SO2 \text{ time} \end{array}$	tsLov	SCK1, SO1 SCK2, SO2	Internal shift clock mode	-200	200	ns	
Valid SI1 → SCK1 ↑ Valid SI1 → SCK1 ↑	tıvsh	SI1, SCK1 SI2, SCK2		1/2 t inst*	_	μs	
$\begin{array}{c} SCK1 \uparrow \to valid \; SI1 \; hold \; time \\ SCK2 \uparrow \to valid \; SI2 \; hold \; time \end{array}$	tsнıx	SCK1, SI1 SCK2, SI2		1/2 t inst*	_	μs	
Serial clock "H" pulse width	tshsl	SCK1, SCK2		1 tinst*	_	μs	
Serial clock "L" pulse width	tslsh	SCK1, SCK2		1 tinst*	_	μs	
$\begin{array}{c} SCK1 \downarrow \to SO1 \text{ time} \\ SCK2 \downarrow \to SO2 \text{ time} \end{array}$	tslov	SCK1, SO1 SCK2, SO2	External shift clock mode	0	200	ns	
Valid SI1 → SCK1 ↑ Valid SI2 → SCK2 ↑	tıvsh	SI1, SCK1 SI2, SCK2		1/2 t inst*	_	μs	
$\begin{array}{c} SCK1 \uparrow \to valid \; SI1 \; hold \; time \\ SCK2 \uparrow \to valid \; SI2 \; hold \; time \end{array}$	tsнıx	SCK1, SI1 SCK2, SI2		1/2 tinst*	_	μs	

^{*:} For information on tinst, see "(4) Instruction Cycle."

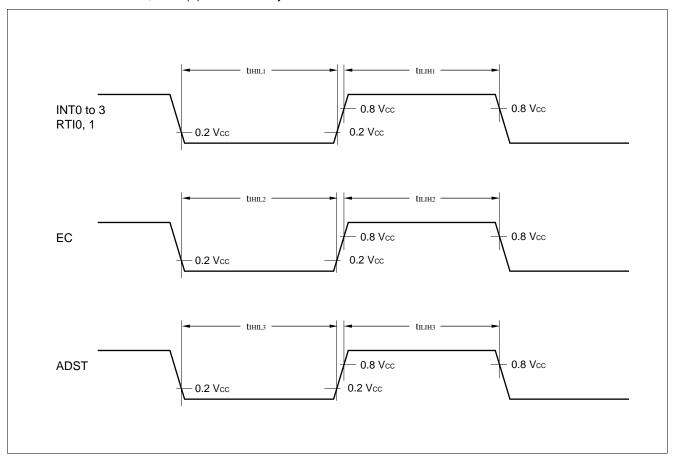


(7) Peripheral Input Timing

 $(Vcc = +5.0 V \pm 10\%, AVss = Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Pin	Condition	Va	lue	Unit	Remarks
Parameter	Symbol	PIII	Condition	Min.	Max.	Ullit	Kemarks
Peripheral input "H" pulse width 1	t ILIH1	RTI0, 1	_	2 tinst*	_	μs	
Peripheral input "L" pulse width 1	t _{IHIL1}	INT0 to INT3	_	∠ l inst	_	μs	
Peripheral input "H" pulse width 2	t ILIH2	- EC	_	1 tinst*	_	μs	
Peripheral input "L" pulse width 2	t IHIL2	LO	_		_	μs	
Peripheral input "H" pulse width 3	t ILIH3		A/D mode 3	32 t _{inst} *	_	μs	
Peripheral input "L" pulse width 3	t ініL3	ADST		32 tinst	_	μs	
Peripheral input "H" pulse width 3	t ILIH3	ADST	0	0.4. *	_	μs	
Peripheral input "L" pulse width 3	tініL3		Sense mode	8 t _{inst} *	_	μs	

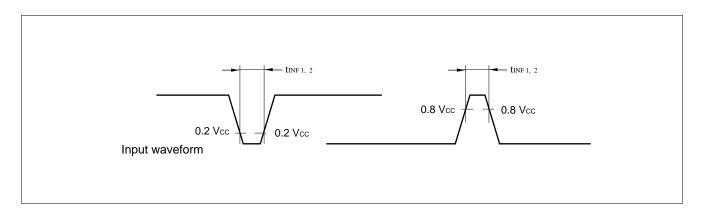
^{*:} For information on tinst, see "(4) Instruction cycle."



(8) Noise Filter

 $(Vcc = +5.0 V\pm 10\%, AVss = Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Pin	Condition	Value		Unit	Remarks
			Condition	Min.	Max.	Offic	Remarks
Noise filter width 1	tinf1	P30 to P37, P40 to P47, P60 to P63	During port operation	15	_	ns	
Noise filter width 2	tinf2	P60 to P63	During external interrupt	60	_	ns	



5. A/D Converter Electrical Characteristics

 $(AVcc = Vcc = +3.5 \text{ V to } 6.0 \text{ V}, AVss = Vss = 0.0 \text{ V}, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

Parameter	Symbol	Pin	Condition	Value			Unit	Remarks
				Min.	Тур.	Max.	Onn	Remarks
Resolution	Vot		_	_	_	8	bit	
Total error			AVR = AVcc	_	_	±2.0	LSB	
Linearity error				_	_	±1.0	LSB	
Differential linearity error				_	_	±0.9	LSB	
Zero transition voltage				AVss – 1.5 LSB	AVss+ 0.5 LSB	AVss+ 2.5 LSB	mV	
Full-scale transition voltage				AVR – 3.5 LSB	AVR – 1.5 LSB	AVR + 0.5 LSB	mV	
Interchannel disparity	_			_	_	1	LSB	
A/D mode conversion time			_	_	44 tisnt*	_	μs	
Sense mode conversion time				_	12 tinst*	_	μs	
Analog port input circuit	lain —	AN0 to AN7		_	_	10	μΑ	
Analog input voltage				0	_	AVR	V	
Reference voltage				0	_	AVcc	V	
Reference voltage supply current	lr	AVR	AVR = 5.0 V when A/D conversion is activated	_	150	_	μА	
	Ігн		AVR = 5.0 V when A/D conversion is stopped	_	_	5	μΑ	

^{*:} For information on tinst, see "(4) Instruction Cycle" in "4. AC Characteristics."

(1) A/D Glossary

Resolution

Analog changes that are identifiable with the A/D converter.

When the number of bits is 8, analog voltage can be divided into $2^8 = 256$.

Linearity error (unit: LSB)

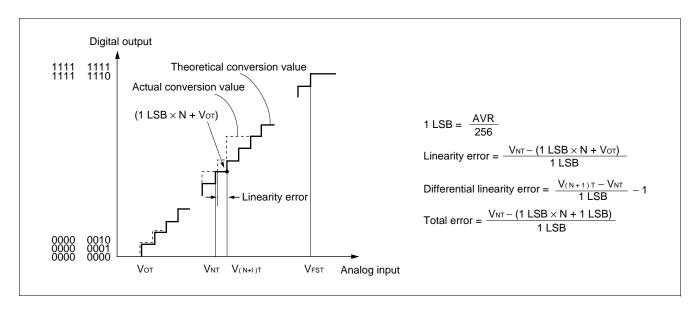
The deviation of the straight line connecting the zero transition point ("0000 0000" \leftrightarrow "0000 0001") with the full-scale transition point ("1111 1111" \leftrightarrow "1111 1110") from actual conversion characteristics

• Differential linearity error (unit: LSB)

The deviation of input voltage needed to change the output code by 1 LSB from the theoretical value

• Total error (unit: LSB)

The difference between theoretical and actual conversion values



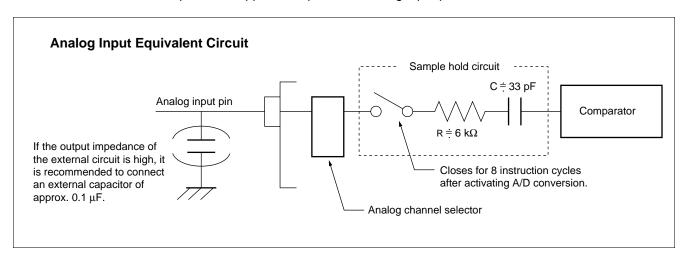
(2) Precautions

• Input impedance of analog input pins

The A/D converter used for the MB89660 series contains a sample hold circuit as illustrated below to fetch analog input voltage into the sample hold capacitor for eight instruction cycles after activating A/D conversion.

For this reason, if the output impedance of the external circuit for the analog input is high, analog input voltage might not stabilize within the analog input sampling period. Therefore, it is recommended to keep the output impedance of the external circuit low. If a higher accurancy is required, set the output impedance in this series to $2 \text{ k}\Omega$ or less.

When the impedance cannot be kept low, the following two methods are recommended. One is to activate the A/D converter continuously for obtaining the pseudo long sampling time by using software. The other is to connect the external capacitor of approx. 0.1 µs to the analog input pin.

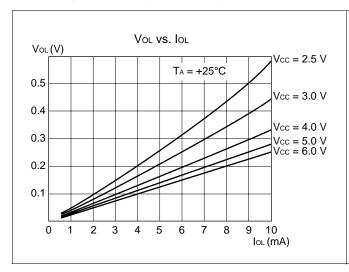


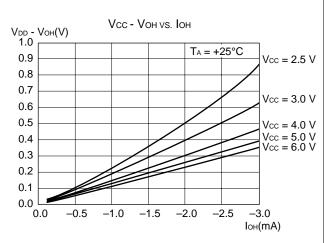
• Error

The smaller the | AVR – AVss |, the greater the error would become relatively.

■ EXAMPLES CHARACTERISTICS

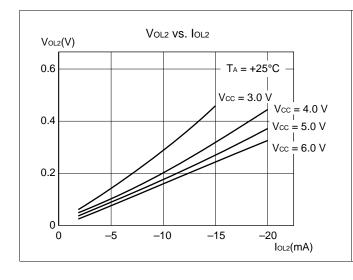
- (1) "L" Level Output Voltage P00 to P07, P10 to P17,P20 to P27, P30, P32 to P36, P40 to P47, P50 to P57, P60 to P63
- (2) "H" Level Output Voltage P00 to P07, P10 to P17, P20 to P27, P30, P32 to P36, P40 to P47, P60 to P63

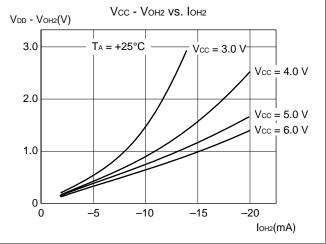




(3) "L" Level Output Voltage P31, P37

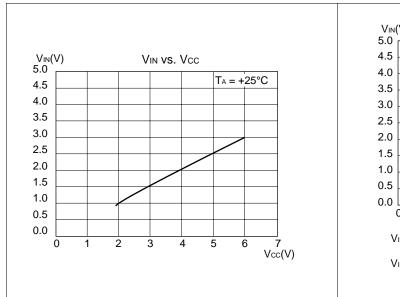
(4) "H" Level Output Voltage P31, P37

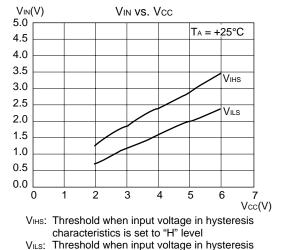




(5) "H" Level Input Voltage/"L" Level Input Voltage (CMOS Input)

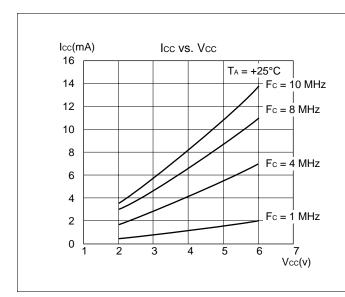
(6) "H" Level Input Voltage/"L" Level Input Voltage (Hysteresis Input)

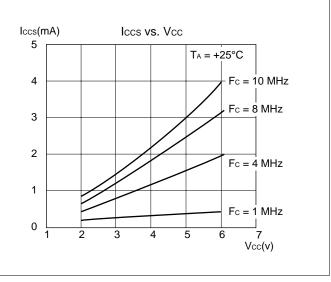




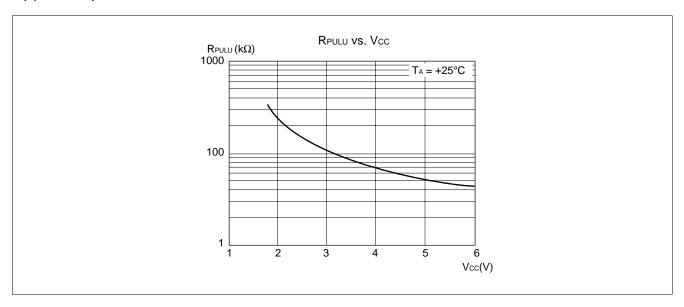
characteristics is set to "L" level

(7) Power Supply Current (External Clock)





(8) Pull-up Resistance



■ INSTRUCTIONS (136 INSTRUCTIONS)

Execution instructions can be divided into the following four groups:

- Transfer
- Arithmetic operation
- Branch
- Others

Table 1 lists symbols used for notation of instructions.

Table 1 Instruction Symbols

Symbol	Meaning
dir	Direct address (8 bits)
off	Offset (8 bits)
ext	Extended address (16 bits)
#vct	Vector table number (3 bits)
#d8	Immediate data (8 bits)
#d16	Immediate data (16 bits)
dir: b	Bit direct address (8:3 bits)
rel	Branch relative address (8 bits)
@	Register indirect (Example: @A, @IX, @EP)
Α	Accumulator A (Whether its length is 8 or 16 bits is determined by the instruction in use.)
AH	Upper 8 bits of accumulator A (8 bits)
AL	Lower 8 bits of accumulator A (8 bits)
Т	Temporary accumulator T (Whether its length is 8 or 16 bits is determined by the instruction in use.)
TH	Upper 8 bits of temporary accumulator T (8 bits)
TL	Lower 8 bits of temporary accumulator T (8 bits)
IX	Index register IX (16 bits)
EP	Extra pointer EP (16 bits)
PC	Program counter PC (16 bits)
SP	Stack pointer SP (16 bits)
PS	Program status PS (16 bits)
dr	Accumulator A or index register IX (16 bits)
CCR	Condition code register CCR (8 bits)
RP	Register bank pointer RP (5 bits)
Ri	General-purpose register Ri (8 bits, i = 0 to 7)
×	Indicates that the very \times is the immediate data. (Whether its length is 8 or 16 bits is determined by the instruction in use.)
(×)	Indicates that the contents of \times is the target of accessing. (Whether its length is 8 or 16 bits is determined by the instruction in use.)
((×))	The address indicated by the contents of \times is the target of accessing. (Whether its length is 8 or 16 bits is determined by the instruction in use.)

Columns indicate the following:

Mnemonic: Assembler notation of an instruction

~: The number of instructions #: The number of bytes Operation: Operation of an instruction

TL, TH, AH: A content change when each of the TL, TH, and AH instructions is executed. Symbols in

the column indicate the following:

• "-" indicates no change.

- dH is the 8 upper bits of operation description data.
- AL and AH must become the contents of AL and AH prior to the instruction executed.

• 00 becomes 00.

N, Z, V, C: An instruction of which the corresponding flag will change. If + is written in this column,

the relevant instruction will change its corresponding flag.

OP code: Code of an instruction. If an instruction is more than one code, it is written according to

the following rule:

Example: 48 to 4F ← This indicates 48, 49, ... 4F.

 Table 2
 Transfer Instructions (48 instructions)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
MOV dir,A	3	2	$(dir) \leftarrow (A)$	_	_	_		45
MOV @IX +off,A	4	2	$((IX) + off) \leftarrow (A)$	_	_	_		46
MOV ext,A	4	3	$(ext) \leftarrow (A)$	_	_	_		61
MOV @EP,A	3	1	$((EP)) \leftarrow (A)$	_	_	_		47
MOV Ri,A	3	1	$(Ri) \leftarrow (A)$	_	_	_		48 to 4F
MOV A,#d8	2	2	$(A) \leftarrow dB'$	AL	_	_	++	04
MOV A,dir	3	2	$(A) \leftarrow (dir)$	AL	_	_	++	05
MOV A,@IX +off	4	2	$(A) \leftarrow ((IX) + off)$	AL	_	_	++	06
MOV A,ext	4	3	$(A) \leftarrow (ext)$	AL	_	_	++	60
MOV A,@A	3	1	$(A) \leftarrow (A)$	AL	_	_	++	92
MOV A,@EP	3	1	$(A) \leftarrow ((EP))$	AL	_	_	++	07
MOV A,Ri	3	1	$(A) \leftarrow (Ri)$	AL	_	_	++	08 to 0F
MOV dir,#d8	4	3	(dír) ← d8	_	_	_		85
MOV @IX +off,#d8	5	3	$((IX) + off) \leftarrow d8$	_	_	_		86
MOV @EP,#d8	4	2	((EP)) ← d8	_	_	_		87
MOV Ri,#d8	4	2	$(Ri) \leftarrow d8$	_	_	_		88 to 8F
MOVW dir,A	4	2	$(dir) \leftarrow (AH), (dir + 1) \leftarrow (AL)$	_	_	_		D5
MOVW @IX +off,A	5	2	$((IX) + off) \leftarrow (AH),$	_	_	_		D6
		_	$((IX) + off + 1) \leftarrow (AL)$					20
MOVW ext,A	5	3	$(ext) \leftarrow (AH), (ext + 1) \leftarrow (AL)$	_	_	_		D4
MOVW @EP,A	4	1	$((EP)) \leftarrow (AH), (EP) + 1) \leftarrow (AL)$	_	_	_		D7
MOVW EPA	2	1	$(EP) \leftarrow (A)$	_	_	_		E3
MOVW A,#d16	3	3	$(A) \leftarrow d16$	AL	АН	dH		E4
MOVW A,dir	4	2	$(AH) \leftarrow (dir), (AL) \leftarrow (dir + 1)$	AL	AH	dH		C5
MOVW A,@IX +off	5	2	$(AH) \leftarrow (IX) + off),$	AL	AH	dH		C6
WOVW A, SIX FOII	3	_	$(AL) \leftarrow ((IX) + OII),$ $(AL) \leftarrow ((IX) + off + 1)$	_	AH	uii		00
MOVW A,ext	5	3	$(AL) \leftarrow ((1X) + 011 + 1)$ $(AH) \leftarrow (ext), (AL) \leftarrow (ext + 1)$	AL	АН	dH	++	C4
MOVW A,@A	4	1	$(AH) \leftarrow (AL), (AL) \leftarrow (AL) \leftarrow (AL)$	AL	AH	dH		93
MOVW A,@EP	4	1	$(AH) \leftarrow (A), (AE) \leftarrow (A) + 1$ $(AH) \leftarrow ((EP)), (AL) \leftarrow ((EP) + 1)$	AL	AH	dH	++	C7
MOVW A, GEP	2	1	$(AII) \leftarrow ((EF)), (AL) \leftarrow ((EF) + I)$ $(A) \leftarrow (EP)$	AL	AII	dH	++	F3
MOVW EP,#d16	3	3	(A) ← (EF) (EP) ← d16		_	u -		E7
MOVW IX,A	2	1		_	_	_		E2
MOVW A,IX	2	1	$ (IX) \leftarrow (A) \\ (A) \leftarrow (IX) $	_	_	dH		F2
	2	1		_				E1
MOVW SP,A MOVW A,SP	2		$(SP) \leftarrow (A)$	_	_	- -		F1
MOV @A,T	3	1	$(A) \leftarrow (SP)$	_	_	dH		
MOV @A,T		1	$((A)) \leftarrow (T)$	_	_	_		82
•	4	1	$((A)) \leftarrow (TH), ((A) + 1) \leftarrow (TL)$	_	_	_		83
MOVW IX,#d16	3	3	$(IX) \leftarrow d16$	_	_	-11.1		E6
MOVW A,PS	2	1	$(A) \leftarrow (PS)$	_	_	dH		70 74
MOVW PS,A	2	1	(PS) ← (A)	_	_	_	++++	71 55
MOVW SP,#d16	3	3	(SP) ← d16	_	_			E5
SWAP	2	1	$(AH) \leftrightarrow (AL)$	_	_	AL		10
SETB dir: b	4	2	(dir): b ← 1	_	_	_		A8 to AF
CLRB dir: b	4	2	(dir): $b \leftarrow 0$	_	_	_		A0 to A7
XCH A,T	2	1	$(AL) \leftrightarrow (TL)$	AL				42
XCHW A,T	3	1	$(A) \leftrightarrow (T)$	AL	AH	dH		43
XCHW A,EP	3	1	$(A) \leftrightarrow (EP)$	_	_	dH		F7
XCHW A,IX	3	1	$(A) \leftrightarrow (IX)$	_	_	dH		F6
XCHW A,SP	3	1	$(A) \leftrightarrow (SP)$	_	_	dH		F5
MOVW A,PC	2	1	(A) ← (PC)	_	_	dH		F0

Operands in more than one operand instruction must be stored in the order in which their mnemonics are written. (Reverse arrangement of F^2MC-8 family)

 Table 3
 Arithmetic Operation Instructions (62 instructions)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
ADDC A,Ri	3	1	$(A) \leftarrow (A) + (Ri) + C$	-	_	_	++++	28 to 2F
ADDC A,#d8	2	2	$(A) \leftarrow (A) + d8 + C$	_	_	_	++++	24
ADDC A,dir	3	2	$(A) \leftarrow (A) + (dir) + C$	_	_	_	++++	25
ADDC A,@IX +off	4	2	$(A) \leftarrow (A) + ((IX) + off) + C$	_	_	_	++++	26
ADDC A,@EP	3	1	$(A) \leftarrow (A) + ((EP)) + C$	_	_	 .	++++	27
ADDCW A	3	1	$(A) \leftarrow (A) + (T) + C$	_	_	dH	++++	23
ADDC A	2	1	(AL) ← (AL) + (TL) + C	_	_	_	++++	22
SUBC A,Ri	3	1	$(A) \leftarrow (A) - (Ri) - C$	_	_	_	++++	38 to 3F
SUBC A,#d8	2	2	$(A) \leftarrow (A) - d8 - C$	_	_	_	++++	34
SUBC A,dir	3	2	$(A) \leftarrow (A) - (dir) - C$	_	_	_	++++	35
SUBC A,@IX +off	4	2	$(A) \leftarrow (A) - ((IX) + off) - C$	_	_	_	++++	36
SUBC A,@EP	3	1	$(A) \leftarrow (A) - ((EP)) - C$	_	_	4L	++++	37
SUBCW A	2	1	$(A) \leftarrow (T) - (A) - C$	_	_	dH	++++	33
SUBC A INC Ri	4	1	$(AL) \leftarrow (TL) - (AL) - C$	_	_	_	++++	32 C9 to CE
INC KI INCW EP	3	1	$(Ri) \leftarrow (Ri) + 1$	_	_	_	+++-	C8 to CF C3
INCW EF	3	1	(EP) ← (EP) + 1	_	_	_		C3 C2
INCW IX	3	1	$(IX) \leftarrow (IX) + 1$	_	_	dH		C2 C0
DEC Ri	4	1	(A) ← (A) + 1 (Ri) ← (Ri) − 1	_	_	uп _	++	D8 to DF
DECW EP	3	1	$(EP) \leftarrow (EP) - 1$	_	_	_	+++-	D8 10 DF
DECW IX	3		$(IX) \leftarrow (IX) - 1$		_	_		D3 D2
DECW A	3	1	$(A) \leftarrow (A) - 1$ $(A) \leftarrow (A) - 1$		_	dH		D2
MULU A	19	1	$(A) \leftarrow (A) - 1$ $(A) \leftarrow (AL) \times (TL)$		_	dH		01
DIVU A	21	1	$(A) \leftarrow (AL) \wedge (TL)$ $(A) \leftarrow (T) / (AL), MOD \rightarrow (T)$	dL	00	00		11
ANDW A	3	1	$(A) \leftarrow (T) \wedge (AL), \text{MOD} \rightarrow (T)$ $(A) \leftarrow (A) \wedge (T)$	- -	_	dH	+ + R -	63
ORW A	3	1	$(A) \leftarrow (A) \lor (T)$	_	_	dH	++R-	73
XORW A	3	li	$(A) \leftarrow (A) \forall (T)$	_	_	dH	++R-	53
CMP A	2	li	(TL) – (AL)	_	_	_	++++	12
CMPW A	3	1	(T) – (A)	_	_	_	++++	13
RORC A	2	1	$rac{}{\hookrightarrow} C \rightarrow A \rightarrow$	_	_	_	++-+	03
ROLC A	2	1	$C \leftarrow A \leftarrow$	_	_	_	++-+	02
CMP A,#d8	2	2	(A) – d8	-	_	_	++++	14
CMP A,dir	3	2	(A) – (dir)	_	_	_	++++	15
CMP A,@EP	3	1	(A) – ((ÉP))	_	_	_	++++	17
CMP A,@IX +off	4	2	(A) - ((IX) + off)	_	_	_	++++	16
CMP A,Ri	3	1	(A) – (Ri)	_	_	_	++++	18 to 1F
DAA	2	1	Decimal adjust for addition	_	_	_	++++	84
DAS	2	1	Decimal adjust for subtraction	_	_	_	++++	94
XOR A	2	1	$(A) \leftarrow (AL) \ \forall \ (TL)$	_	_	_	++R-	52
XOR A,#d8	2	2	$(A) \leftarrow (AL) \forall d8$	_	_	_	++R-	54
XOR A,dir	3	2	$(A) \leftarrow (AL) \ \forall \ (dir)$	_	_	_	+ + R –	55
XOR A,@EP	3	1	$(A) \leftarrow (AL) \ \forall \ (\ (EP) \)$	_	_	_	+ + R –	57
XOR A,@IX +off	4	2	$(A) \leftarrow (AL) \ \forall \ (\ (IX) + off)$	_	_	-	+ + R –	56
XOR A,Ri	3	1	$(A) \leftarrow (AL) \ \forall \ (Ri)$	_	_	_	+ + R –	58 to 5F
AND A	2	1	$(A) \leftarrow (AL) \land (TL)$	_	_	-	+ + R –	62
AND A,#d8	2	2	$(A) \leftarrow (AL) \land d8$	_	_	_	+ + R –	64
AND A,dir	3	2	$(A) \leftarrow (AL) \land (dir)$	_	_	_	+ + R –	65

(Continued)

(Continued)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
AND A,@EP	3	1	$(A) \leftarrow (AL) \land ((EP))$	_	_	_	++R-	67
AND A,@IX +off	4	2	$(A) \leftarrow (AL) \land ((IX) + off)$	_	_	_	++R-	66
AND A,Ri	3	1	$(A) \leftarrow (AL) \land (Ri)$	_	_	_	++R-	68 to 6F
OR A	2	1	$(A) \leftarrow (AL) \lor (TL)$	_	_	_	++R-	72
OR A,#d8	2	2	$(A) \leftarrow (AL) \lor d8$	_	_	_	++R-	74
OR A,dir	3	2	$(A) \leftarrow (AL) \lor (dir)$	_	_	_	++R-	75
OR A,@EP	3	1	$(A) \leftarrow (AL) \lor ((EP))$	_	_	_	++R-	77
OR A,@IX +off	4	2	$(A) \leftarrow (AL) \lor ((IX) + off)$	_	_	_	++R-	76
OR A,Ri	3	1	$(A) \leftarrow (AL) \lor (Ri)$	_	_	_	++R-	78 to 7F
CMP dir,#d8	5	3	(dir) – d8	_	_	_	++++	95
CMP @EP,#d8	4	2	((EP)) – d8	_	_	_	++++	97
CMP @IX +off,#d8	5	3	((IX) + off) - d8	_	_	_	++++	96
CMP Ri,#d8	4	2	(Ri) – d8	_	_	_	++++	98 to 9F
INCW SP	3	1	(SP) ← (SP) + 1	_	_	_		C1
DECW SP	3	1	(SP) ← (SP) – 1	_	-	_		D1

Table 4 Branch Instructions (17 instructions)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
BZ/BEQ rel	3	2	If $Z = 1$ then $PC \leftarrow PC + rel$	-	_	_		FD
BNZ/BNE rel	3	2	If $Z = 0$ then $PC \leftarrow PC + rel$	_	_	_		FC
BC/BLO rel	3	2	If C = 1 then PC ← PC + rel	_	_	_		F9
BNC/BHS rel	3	2	If $C = 0$ then $PC \leftarrow PC + rel$	_	_	_		F8
BN rel	3	2	If N = 1 then PC ← PC + rel	_	_	_		FB
BP rel	3	2	If N = 0 then PC \leftarrow PC + rel	_	_	_		FA
BLT rel	3	2	If $V \forall N = 1$ then $PC \leftarrow PC + rel$	_	_	_		FF
BGE rel	3	2	If $V \forall N = 0$ then $PC \leftarrow PC + rel$	_	_	_		FE
BBC dir: b,rel	5	3	If (dir: b) = 0 then PC \leftarrow PC + rel	_	_	_	-+	B0 to B7
BBS dir: b,rel	5	3	If (dir: b) = 1 then PC \leftarrow PC + rel	_	_	_	-+	B8 to BF
JMP @A	2	1	(PC) ← (A)	_	_	_		E0
JMP ext	3	3	(PC) ← ext	_	_	_		21
CALLV #vct	6	1	Vector call	_	_	_		E8 to EF
CALL ext	6	3	Subroutine call	_	_	_		31
XCHW A,PC	3	1	$(PC) \leftarrow (A), (A) \leftarrow (PC) + 1$	_	_	dΗ		F4
RET	4	1	Return from subrountine	_	_	_		20
RETI	6	1	Return form interrupt	_	_	_	Restore	30

Table 5 Other Instructions (9 instructions)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
PUSHW A	4	1		_	_	_		40
POPW A	4	1		_	_	dΗ		50
PUSHW IX	4	1		_	_	_		41
POPW IX	4	1		_	_	_		51
NOP	1	1		_	_	_		00
CLRC	1	1		_	_	_	R	81
SETC	1	1		_	_	_	S	91
CLRI	1	1		_	_	_		80
SETI	1	1		_	_	_		90

■ INSTRUCTION MAP

	O															
ш	MOVW A,PC	MOVW A,SP	MOVW A,IX	MOVW A,EP	XCHW A,PC	XCHW A,SP	XCHW A,IX	XCHW A,EP	BNC rel	BC rel	BP rel	BN rel	BNZ rel	BZ rel	BGE rel	BLT rel
ш	JMP @A	MOVW N SP,A	MOVW N	MOVW N	MOVW X A,#d16	MOVW X SP,#d16	MOVW X	MOVW X EP,#d16	CALLV B							
۵	DECW J	DECW N	DECW IX	DECW N	MOWW N	MOVW N	MOVW NGIX+d,A	MOVW N @EP,A	RO	2	22	83	R4	R5	R6	R7
	A DE						_	Ž	DEC							
ပ	INCW	INCW SP	INCW	INCW	MOVW A,ext	MOVW A,dir	MOVW A,@IX+d	MOVW A, @EP	INC R0	INC R1	INC R2	INC R3	INC R4	INC R5	INC R6	INC R7
В	BBC dir: 0,rel	BBC dir: 1,rel	BBC dir: 2,rel	BBC dir: 3,rel	BBC dir: 4,rel	BBC dir: 5,rel	BBC dir: 6,rel	BBC dir: 7,rel	BBS dir: 0,rel	BBS dir: 1,rel	BBS dir: 2,rel	BBS dir: 3,rel	BBS dir: 4,rel	BBS dir: 5,rel	BBS dir: 6,rel	BBS dir: 7,rel
٨	CLRB dir: 0	CLRB dir: 1	CLRB dir: 2	CLRB dir: 3	CLRB dir: 4	CLRB dir: 5	CLRB dir: 6	CLRB dir: 7	SETB dir: 0	SETB dir: 1	SETB dir: 2	SETB dir: 3	SETB dir: 4	SETB dir: 5	SETB dir: 6	SETB dir: 7
6	SETI	SETC	MOV A,@A	MOVW A,@A	DAS	CMP dir,#d8	CMP @IX +d,#d8	CMP @EP;#d8	CMP R0,#d8	CMP R1,#d8	CMP R2,#d8	CMP R3,#d8	CMP R4,#d8	CMP R5,#d8	CMP R6,#d8	CMP R7,#d8
8	CLRI	CLRC	MOV @A,T	MOVW @A,T	DAA	MOV dir,#d8	MOV @IX +d,#d8	MOV @EP;#d8	MOV R0,#d8	MOV R1,#d8	MOV R2,#d8	MOV R3,#d8	MOV R4,#d8	MOV R5,#d8	MOV R6,#d8	MOV R7,#d8
7	MOVW A,PS	MOVW PS,A	OR A	ORW A	OR A,#d8	OR A,dir	OR A,@IX +d	OR A,@EP	OR A,R0	OR A,R1	OR A,R2	OR A,R3	OR A,R4	OR A,R5	OR A,R6	OR A,R7
9	MOV A,ext	MOV ext,A	AND	ANDW A	AND A,#d8	AND A,dir	AND A,@IX +d	AND A,@EP	AND A,R0	AND A,R1	AND A,R2	AND A,R3	AND A,R4	AND A,R5	AND A,R6	AND A,R7
35	POPW A	POPW IX	XOR A	XORW A	XOR A,#d8	XOR A,dir	XOR A,@IX +d	XOR A,@EP	XOR A,R0	XOR A,R1	XOR A,R2	XOR A,R3	XOR A,R4	XOR A,R5	XOR A,R6	XOR A,R7
4	PUSHW A	PUSHW IX	XCH A, T	XCHW A, T		MOV dir,A	MOV @IX +d,A	MOV @EP,A	MOV R0,A	MOV R1,A	MOV R2,A	MOV R3,A	MOV R4,A	MOV R5,A	MOV R6,A	MOV R7,A
3	RETI	CALL addr16	SUBC A	SUBCW	SUBC A,#d8	SUBC A,dir	SUBC A,@IX +d	SUBC A,@EP	SUBC A,R0	SUBC A,R1	SUBC A,R2	SUBC A,R3	SUBC A,R4	SUBC A,R5	SUBC A,R6	SUBC A,R7
2	RET	JMP addr16	ADDC A	ADDCW A	ADDC A,#d8	ADDC A,dir	ADDC A,@IX +d	ADDC A,@EP	ADDC A,R0	ADDC A,R1	ADDC A,R2	ADDC A,R3	ADDC A,R4	ADDC A,R5	ADDC A,R6	ADDC A,R7
-	SWAP	DIVU	CMP	CMPW	CMP A,#d8	CMP A,dir	CMP A,@IX +d	CMP A,@EP	CMP A,R0	CMP A,R1	CMP A,R2	CMP A,R3	CMP A,R4	CMP A,R5	CMP A,R6	CMP A,R7
0	NOP	MULU A	ROLC A	RORC A	MOV A,#d8	MOV A,dir	MOV A,@IX+d	MOV A,@EP	MOV A,R0	MOV A,R1	MOV A,R2	MOV A,R3	MOV A,R4	MOV A,R5	MOV A,R6	MOV A,R7
L H	0	1	2	က	4	2	9	7	œ	6	4	a	ပ	۵	ш	ш

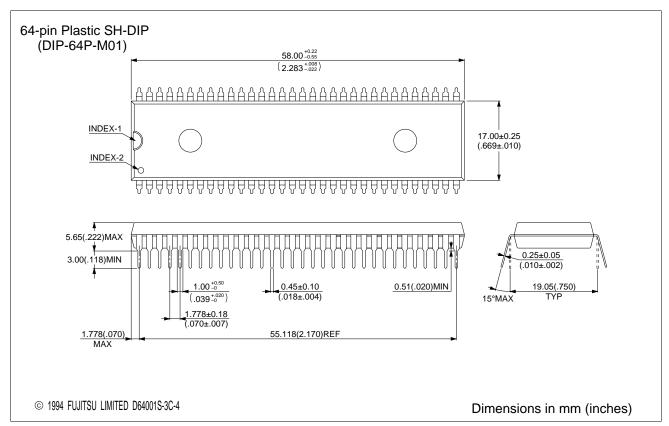
■ MASK OPTIONS

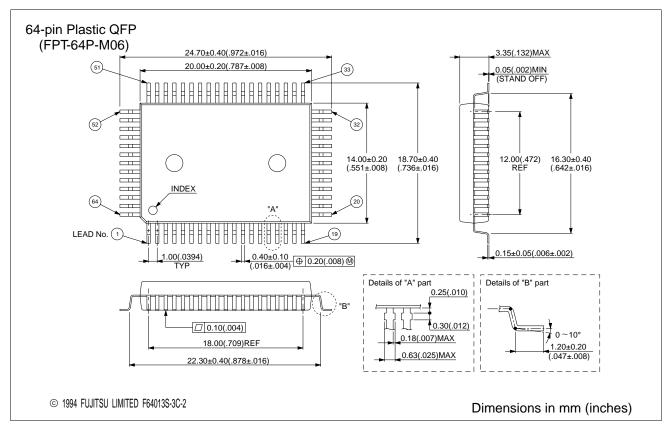
No.	Part number	MB89663 MB89665	MB89P665 MB89W665		
NO.	Specifying procedure	Specify when ordering masking	Set with EPROM programmer		
1	Power-on reset selection With power-on reset Without power-on reset	Selectable	Setting possible		
2	Selection of the oscillation stabilization time Crystal oscillator (26.2 ms/10 MHz) Ceramic oscillator (1.64 ms/10 MHz)	Selectable	Setting possible		
3	Reset pin output With reset output Without reset output	Selectable	Setting possible		
4	Pull-up resistors P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P60 to P63	Can be selected per pin. (P50 to P57 are available for without pull-up resistors when an A/D converter is used.)	Can be set per pin. (P54 to P57 must have the same setting)		

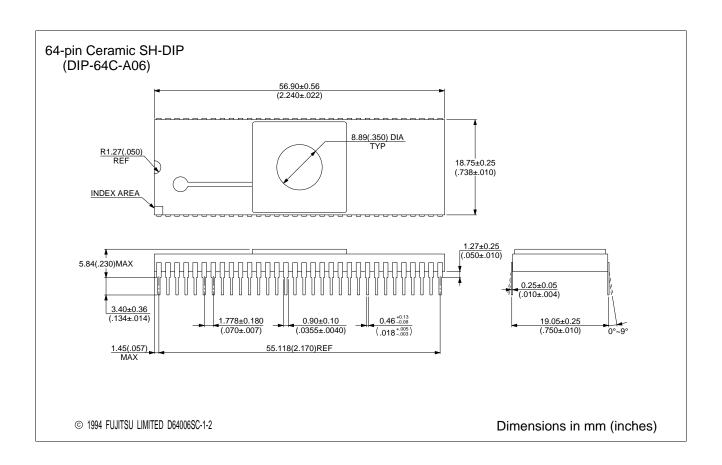
■ ORDERING INFORMATION

Part number	Package	Remarks
MB89663P-SH MB89665P-SH MB89P665P-SH	64-pin Plastic SH-DIP (DIP-64P-M01)	
MB89663PF MB89665PF MB89P665PF	64-pin Plastic SH-DIP (FPT-64P-M06)	
MB89W665C-SH	64-pin Ceramic SH-DIP (DIP-64C-A06)	

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